

Specification for an LC Filter MtronPTI P/N: LF9211

I. GENERAL & ELECTRICAL REQUIREMENTS:

1. Center Frequency, F_{ON} : 208.16MHz
2. PASSBAND @ 3dB: $F_{ON} \pm 25.0$ MHz minimum
3. INSERTION LOSS (at peak of transmission): 2.5dB maximum
4. RETURN LOSS ($F_{ON} \pm 25.0$ MHz): 15.0dB minimum
5. REJECTION (minimum)
 - 60dB: $F_{ON} \pm 43.0$ MHz maximum
6. DIFFERENTIAL DELAY (over $F_{ON} \pm 20$ MHz): 18ns maximum
7. Z_{IN}/Z_{OUT} : 50Ω nominal

II. ENVIRONMENTAL & PHYSICAL REQUIREMENTS:

1. TEMPERATURE RANGE
 - Operating (full specification compliance): -55°C to +85°C
 - Storage: -55°C to +105°C
2. PACKAGE: SMD (See Figure 1)

Note 1: Materials

- a. The upper housing is silver plated brass
- b. The base is Rogers 4350 dielectric or equivalent
- c. Sn10Pb88Ag02 solder will be utilized throughout the construction of this device
- d. No pure tin components are utilized
- e. The SMD pad finish is ENIG per IPC-4552

Note 2: Seal & Processes

- a. The device is solder sealed
- b. The device is compatible with automated assembly processes
 - Automated pick & place
 - Reflow soldering (see reflow profile Figure 3)
 - Post reflow aqueous and non-aqueous wash

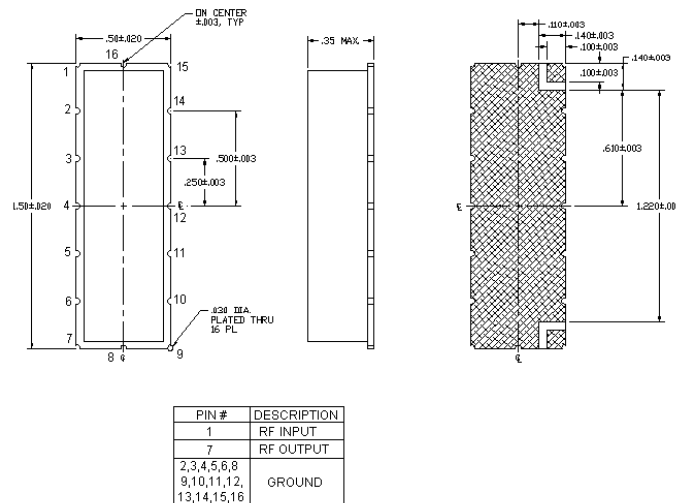


Figure 1: Package Outline Drawing

Specification for an LC Filter

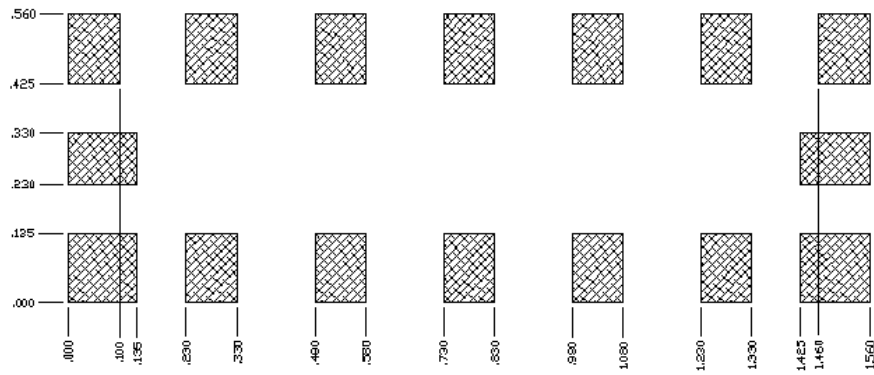


Figure 2: Recommended PAD layout

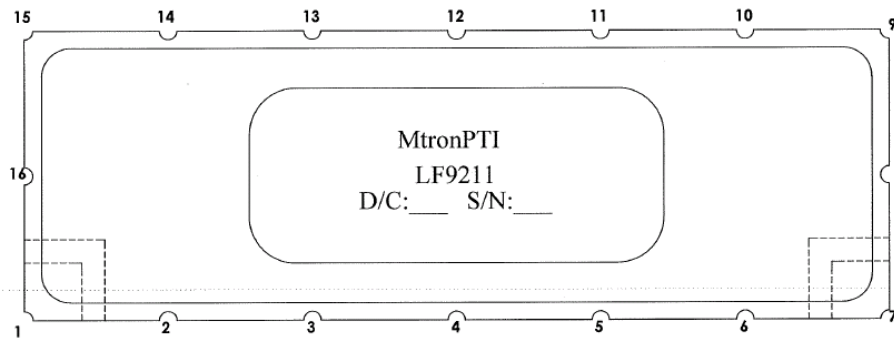


Figure 3: Part marking

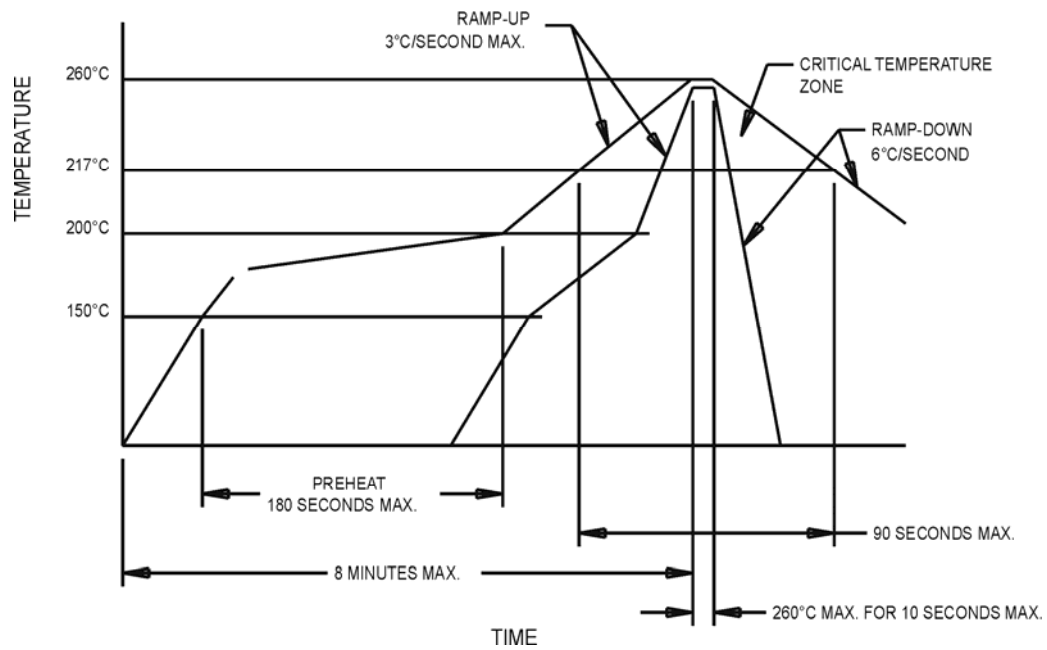


Figure 4: Recommended Reflow Profile

III. Datasheet Revision Table

Date	Rev	Author	Comment
04-09-20	F	BRR	Solder type corrected from Sn96 to Sn10, outline revised, center frequency added.
03-30-20	E	BRR	SMD Pad finish updated
04-12-19	D	BRR	Part marking outline added
04-01-15	C	DPD	Differential delay updated
12-01-10	B	BM	Solder profile added
-	A	BM	Preliminary Release